Initial Product/Process Change Notification
Document #:IPCN25021X
Issue Date:14 Dec 2022

Title of Change:	Qualify 0.5um silicon on insulator backlapping & Si etch on Vanguard International Semiconductor Corporation FAB2 as 2nd source.
Proposed First Ship date:	31 Aug 2023 or earlier if approved by customer
Contact Information:	Contact your local onsemi Sales Office or Wayne.Cheng@onsemi.com
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>
Marking of Parts/ Traceability of Change:	The affected products will be identified with date code
Change Category:	Wafer Fab Change
Change Sub-Category(s):	Manufacturing Site Addition

Sites Affected:

onsemi Sites	**External Foundry/Subcon Sites**
None	Vanguard International Semiconductor, Taiwan

Description and Purpose:

Vanguard International Semiconductor Corporation plans to release silicon on insulator backside grinding and Si etching as 2nd source at FAB2 to extend capacity & reduce outsourced channel (Phoenix Silicon International) potential delivery risk. It will make delivery smoothly to avoid lot delivery delay.

- Post Fab Location (BGBM/ Bump…etc): change

	From	**To**
Post Fab Location (BGBM/ Bump…etc)	Phoenix Silicon International (BG)	Phoenix Silicon International (BG) / Vanguard International Semiconductor Corporation FAB2

There is no product marking change as a result of this change

Qualification Plan:

QV DEVICE NAME: NCP81075DR2G
RMS: TBD
PACKAGE: SOIC-8N

Test	Specification	Condition	Interval
PC	J-STD-020 JESD-A113	MSL 1 IR reflow at 260 °C	
TC+PC	JESD22-A104	Ta= -65°C to +150°C	500 cyc

List of Affected Parts:

Note: *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal.***

Part Number	Qualification Vehicle
NCP81075DR2G	NCP81075DR2G
NCP81080DR2G	NCP81075DR2G
NCP81080MNTBG	NCP81075DR2G